

## The RF Line

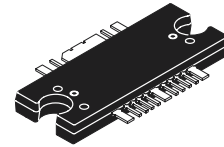
# RF LDMOS Integrated Power Amplifiers

The MWIC930 wideband integrated circuit is designed for CDMA and GSM/GSM EDGE applications. It uses Motorola's newest High Voltage (26 to 28 Volts) LDMOS IC technology and integrates a multi-stage structure. Its wideband On Chip integral matching circuitry makes it usable from 746 to 960 MHz. The linearity performances cover all modulations for cellular applications: GSM, GSM EDGE, TDMA, N-CDMA and W-CDMA.

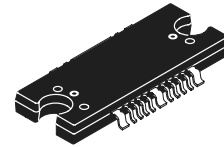
- Typical CDMA Performance: 27 Volts,  $I_{DQ1} = 90$  mA,  $I_{DQ2} = 240$  mA, 2-Carrier N-CDMA, IS -95, 869-894 MHz, 1.2288 MHz Channel Bandwidth, IM3 Measured in 1.2288 Integrated Bandwidth, ACPR Measured in 30 kHz Integrated Bandwidth, 2.5 MHz Carrier Spacing  
Output Power — 5 Watts (Avg.)  
Power Gain — 31 dB  
Efficiency — 21%  
Adjacent Channel Power — -52 dBc  
IRL — -14 dB
- Typical Performance @ P1dB: 921-960 MHz, 26 Volts  
Output Power — 30 Watts P1dB  
Power Gain — 30 dB  
Efficiency — 45%
- On Chip Matching (50 Ohm Input, >4 Ohm Output)
- Integrated Temperature Compensation Capability
- Integrated ESD Protection
- Usable for SCPA and MCPA Architecture
- Capable of Handling 5:1 VSWR, @ 26 Vdc,  $f = 921$  MHz,  $P_{out} = 30$  W CW,  $I_{DQ1} = 90$  mA,  $I_{DQ2} = 240$  mA
- Can Be Bolted or Soldered through a Hole in the Circuit Board for Maximum Thermal Performance
- Also Available in Gull Wing for Surface Mount
- Available in Tape and Reel. R1 Suffix = 500 Units per 44 mm, 13 inch Reel.

## MWIC930R1 MWIC930GR1

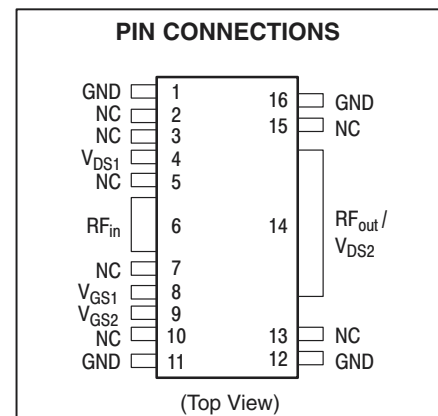
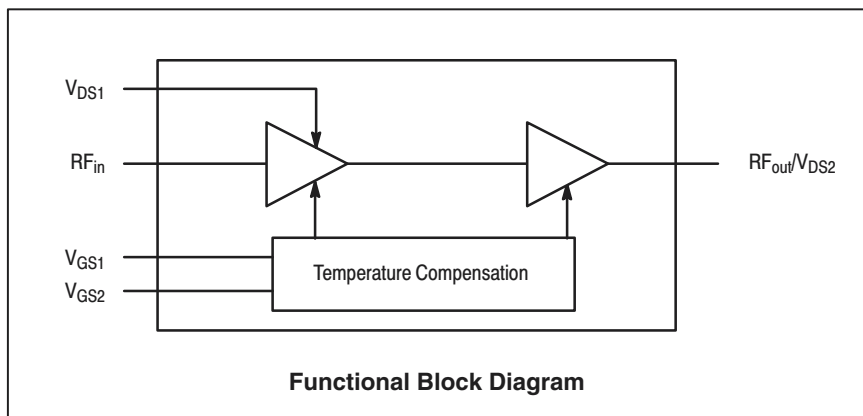
**N-CDMA, W-CDMA,  
GSM/GSM EDGE, 746 – 960 MHz,  
30 W, 26–28 V RF LDMOS  
INTEGRATED POWER AMPLIFIERS**



**CASE 1329-08  
TO-272 WIDE BODY MULTI-LEAD  
PLASTIC  
MWIC930R1**



**CASE 1329A-02  
TO-272 WIDE BODY MULTI-LEAD  
GULL WING  
PLASTIC  
MWIC930GR1**



**MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Drain–Source Voltage	$V_{DSS}$	65	Vdc
Gate–Source Voltage	$V_{GS}$	–0.5, +15	Vdc
Storage Temperature Range	$T_{stg}$	–65 to +175	°C
Operating Junction Temperature	$T_J$	175	°C

**THERMAL CHARACTERISTICS**

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$		°C/W
GSM Application ( $P_{out} = 30$ W CW)	Stage 1, 27 Vdc, $I_{DQ} = 90$ mA Stage 2, 27 Vdc, $I_{DQ} = 240$ mA	1.22	
GSM EDGE Application ( $P_{out} = 15$ W CW)	Stage 1, 27 Vdc, $I_{DQ} = 90$ mA Stage 2, 27 Vdc, $I_{DQ} = 240$ mA	1.39	
CDMA Application ( $P_{out} = 5$ W CW)	Stage 1, 27 Vdc, $I_{DQ} = 90$ mA Stage 2, 27 Vdc, $I_{DQ} = 240$ mA	1.50	

**ESD PROTECTION CHARACTERISTICS**

Test Conditions	Class
Human Body Model	1 (Minimum)
Machine Model	M3 (Minimum)
Charge Device Model	C2 (Minimum)

**MOISTURE SENSITIVITY LEVEL**

Test Methodology	Rating
Per JESD 22–A113	3

**ELECTRICAL CHARACTERISTICS** ( $T_C = 25^\circ\text{C}$ , unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
----------------	--------	-----	-----	-----	------

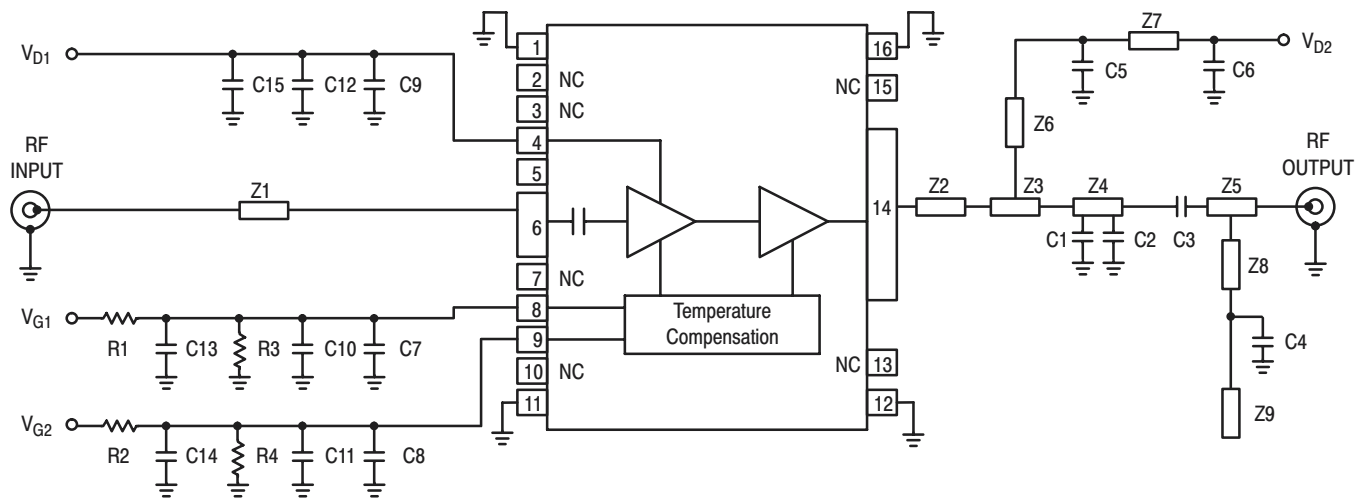
**CDMA FUNCTIONAL TESTS** (In Motorola CDMA Test Fixture, 50 ohm system) 1–Carrier N–CDMA, 869–894 MHz, IS–95 CDMA Pilot, Sync, Paging, Traffic Codes 8 through 13.

Common–Source Amplifier Power Gain ( $V_{DD} = 27$ Vdc, $P_{out} = 5$ W Avg., 1–Carrier N–CDMA, $I_{DQ1} = 90$ mA, $I_{DQ2} = 240$ mA, $f = 869$ – $894$ MHz)	$G_{ps}$	28	31	—	dB
Drain Efficiency ( $V_{DD} = 27$ Vdc, $P_{out} = 5$ W Avg., 1–Carrier N–CDMA, $I_{DQ1} = 90$ mA, $I_{DQ2} = 240$ mA, $f = 869$ – $894$ MHz)	$\eta$	18	21	—	%
Adjacent Channel Power Ratio ( $V_{DD} = 27$ Vdc, $P_{out} = 5$ W Avg., 1–Carrier N–CDMA, $I_{DQ1} = 90$ mA, $I_{DQ2} = 240$ mA, $f = 869$ – $894$ MHz)	ACPR	—	–52	–48	dBc
Input Return Loss ( $V_{DD} = 27$ Vdc, $P_{out} = 5$ W Avg., 1–Carrier N–CDMA, $I_{DQ1} = 90$ mA, $I_{DQ2} = 240$ mA, $f = 880$ MHz)	IRL	—	–12	–9	dB

(continued)

**ELECTRICAL CHARACTERISTICS – continued** ( $T_C = 25^\circ\text{C}$ , unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>PERFORMANCE TESTS</b> (In Motorola Test Fixture) $V_{DS} = 26\text{ V}$ , $I_{DQ1} = 90\text{ mA}$ , $I_{DQ2} = 240\text{ mA}$					
Quiescent Current Accuracy over Temperature (–10 to 85°C) at Nominal Value	$\Delta I_{QT}$	—	±5	—	%
Gain Flatness in 80 MHz Bandwidth @ $P_{out} = 5\text{ W CW}$ (Characterize from 840–920 MHz)	$G_F$	—	0.3	—	dB
Deviation from Linear Phase in 80 MHz Bandwidth @ $P_{out} = 5\text{ W CW}$ (Characterize from 840–920 MHz)	$\Phi$	—	0.6	—	°
Delay @ $P_{out} = 5\text{ W CW}$	Delay	—	3	—	ns
Insertion Phase Window @ $P_{out} = 5\text{ W CW}$	$\Phi\Delta$	—	±15	—	°
<b>GSM/GSM EDGE FUNCTIONAL TESTS</b> (In Motorola GSM Test Fixture) $V_{DS} = 27\text{ V}$ , $I_{DQ1} = 90\text{ mA}$ , $I_{DQ2} = 240\text{ mA}$ , 921–960 MHz, CW					
Output Power at 1dB Compression Point	P1dB	—	30	—	Watts
Common–Source Amplifier Power Gain @ P1dB	$G_{ps}$	—	30	—	dB
Drain Efficiency @ P1dB	$\eta$	—	45	—	%
Input Return Loss @ P1dB	IRL	—	–12	—	dB
Third Order Intermodulation Distortion (15 W, 2–Tone 100 kHz Spacing)	IMD3	—	–30	—	dBc
Third Order Intermodulation Distortion (1 W, 2–Tone 100 kHz Tone Spacing)	IMD3 backoff	—	–45	—	dBc
Gain Flatness 921–960 MHz @ $P_{out} = 5\text{ W CW}$	$G_F$	—	0.3	—	dB
Deviation from Linear Phase 921–960 MHz @ $P_{out} = 5\text{ W CW}$	$\Phi$	—	0.6	—	°



- |    |  |     |  |
|----|--|-----|--|
| Z1 | 0.0438" x 0.970" 50 Ω Microstrip<br>(not including lead pad) | Z5  | 0.0438" x 0.2009" Microstrip             |
| Z2 | 0.234" x 0.1183" Microstrip<br>(including lead pad)          | Z6  | 0.0504" x 0.528" Microstrip              |
| Z3 | 0.1575" x 0.0938" Microstrip                                 | Z7  | 0.0504" x 0.150" Microstrip              |
| Z4 | 0.08425" x 0.584" Microstrip                                 | Z8  | 0.0254" x 0.880" Microstrip              |
|    |  | Z9  | 0.0254" x 0.250" Microstrip              |
|    |  | PCB | Rogers 4350, 0.020", $\epsilon_r = 3.50$ |

Figure 1. 746–960 MHz Test Fixture Schematic

Table 1. 746–960 MHz Test Fixture Component Designations and Values

Part	Description	Value, P/N or DWG	Manufacturer
*C1	15 pF High Q Capacitor	ATC600S150JW	ATC
*C2	6.8 pF High Q Capacitor – GSM Fixture 8.2 pF High Q Capacitor – CDMA Fixture	ATC600S6R8CW ATC600S8R2CW	ATC
*C3	5.6 pF High Q Capacitor	ATC600S5R6CW	ATC
*C4, C5, C7, C8, C9	47 pF High Q Capacitors	ATC600S470JW	ATC
C6, C13, C14, C15	1 μF Chip Capacitors	GRM42–2X7R105K050AL	Murata
C10, C11, C12	10 nF Chip Capacitors	C0603C103J5R	Kemet
R1, R2	1 kΩ, 1/8 W Chip Resistors	RM73B2AT102J	KOA Speer
R3, R4	1 MΩ, 1/4 W Chip Resistors	RM73B2BT105J	KOA Speer

\* For output matching and bypass purposes, it is strongly recommended to use these exact capacitors.

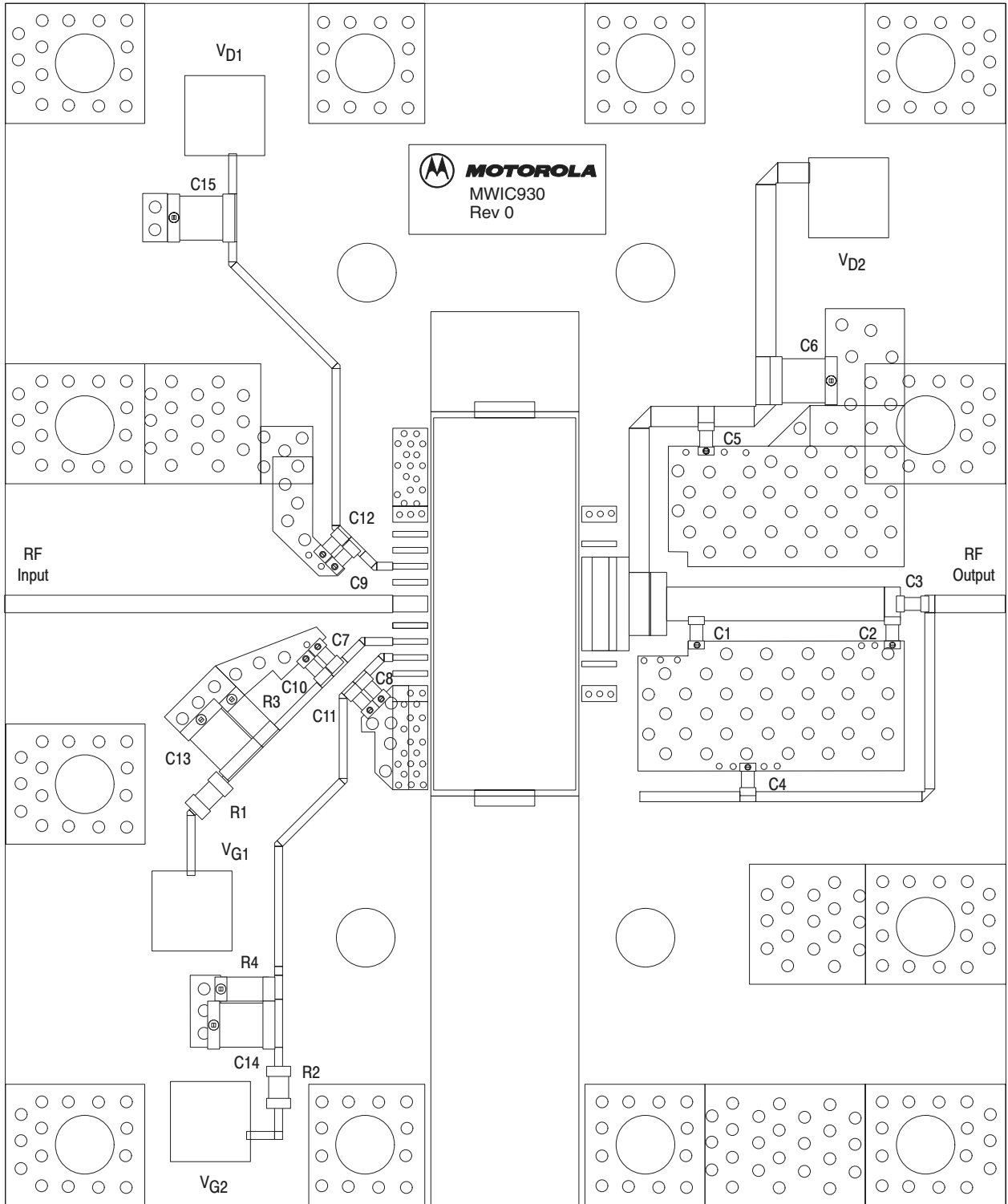
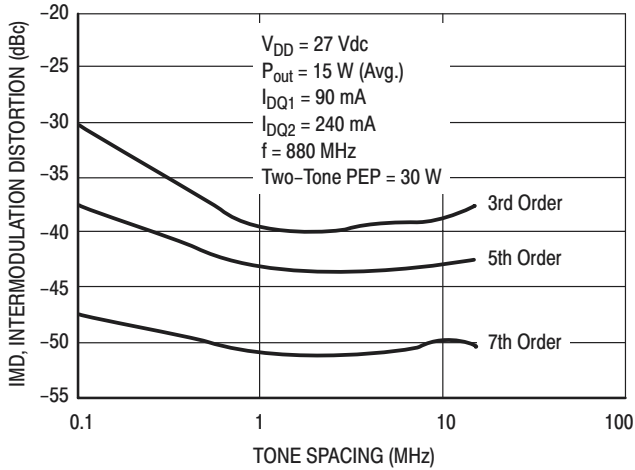
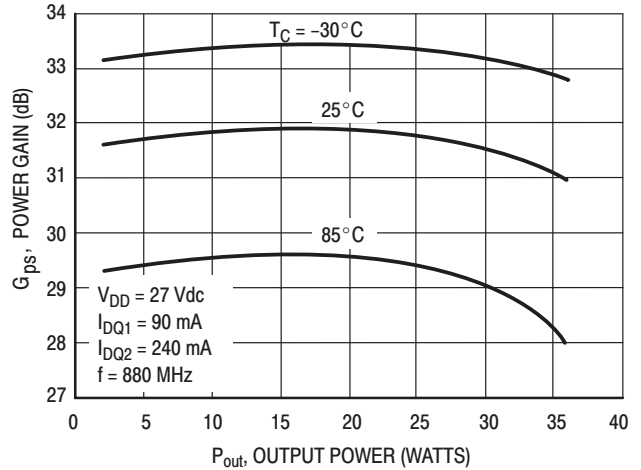


Figure 2. 746–960 MHz Test Circuit Component Layout

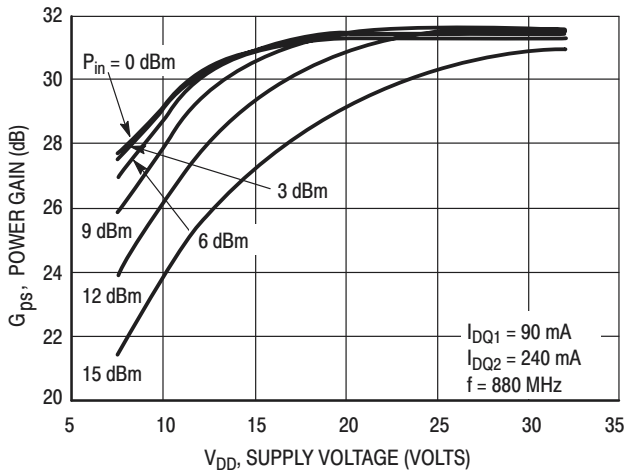
## TYPICAL CHARACTERISTICS



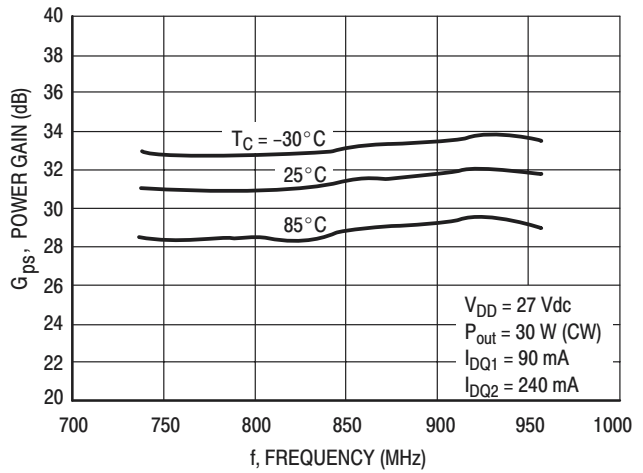
**Figure 3. Two-Tone Broadband Performance**



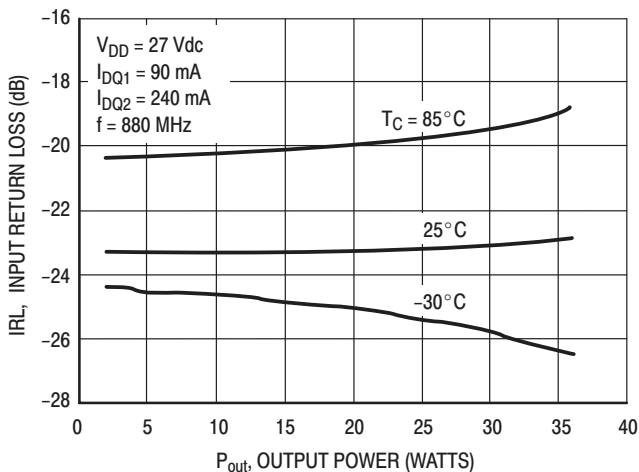
**Figure 4. Power Gain versus Output Power**



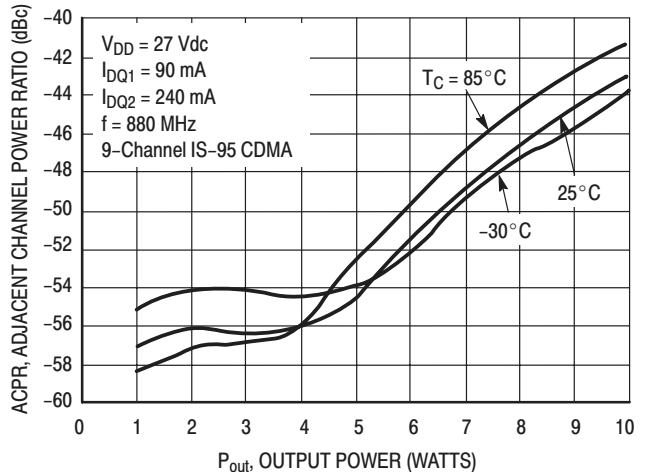
**Figure 5. Power Gain versus Supply Voltage**



**Figure 6. Power Gain versus Frequency**

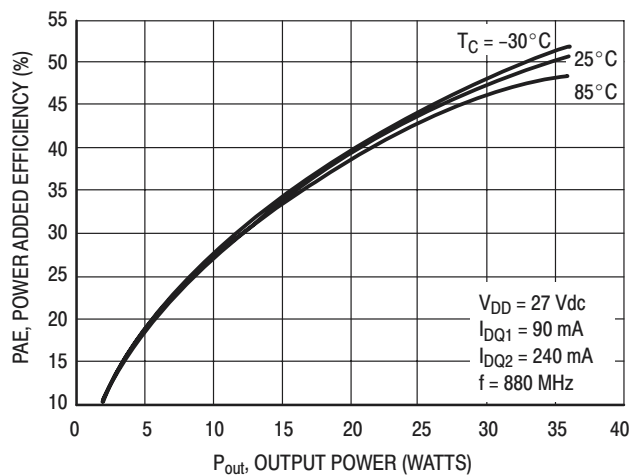


**Figure 7. Input Return Loss versus Output Power**

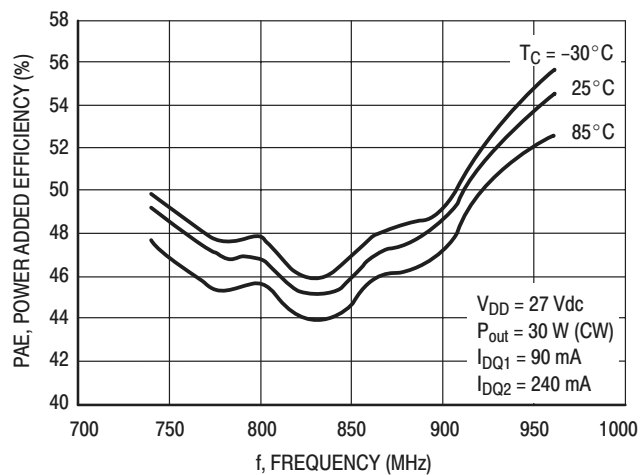


**Figure 8. Adjacent Channel Power Ratio versus Output Power**

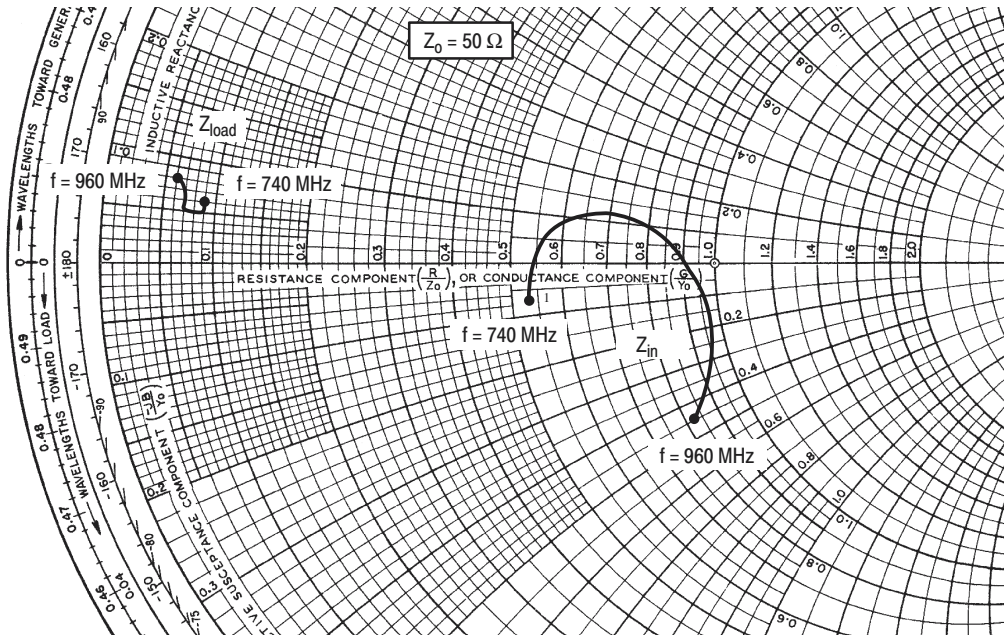
## TYPICAL CHARACTERISTICS



**Figure 9. Power Added Efficiency versus Output Power**



**Figure 10. Power Added Efficiency versus Frequency**



$V_{DD} = 27 \text{ Vdc}$ ,  $I_{DQ1} = 90 \text{ mA}$ ,  $I_{DQ2} = 240 \text{ mA}$ ,  $P_{out} = 5 \text{ W Avg.}$

f MHz	$Z_{in}$ $\Omega$	$Z_{load}$ $\Omega$
740	$26.61 - j3.68$	$4.28 + j2.99$
760	$26.88 - j0.53$	$4.37 + j2.91$
780	$28.22 + j2.21$	$4.39 + j2.79$
800	$30.57 + j4.31$	$4.34 + j2.64$
820	$33.79 + j5.53$	$4.21 + j2.54$
840	$37.83 + j5.30$	$4.06 + j2.52$
860	$41.92 + j3.42$	$3.90 + j2.58$
880	$45.58 - j0.40$	$3.73 + j2.70$
900	$47.77 - j5.84$	$3.59 + j2.93$
920	$47.83 - j12.15$	$3.43 + j3.17$
940	$45.55 - j18.05$	$3.28 + j3.44$
960	$41.58 - j22.64$	$3.13 + j3.75$

$Z_{in}$  = Device input impedance as measured from RF input to ground.

$Z_{load}$  = Test circuit impedance as measured from drain to ground.

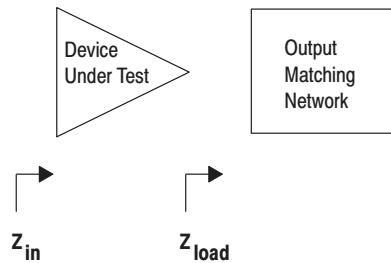
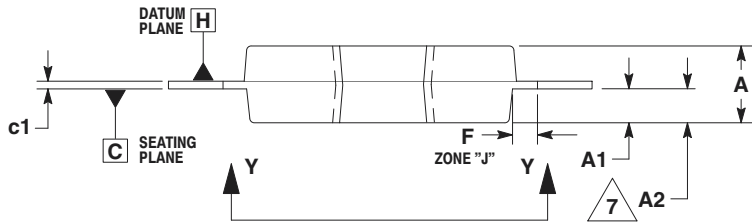
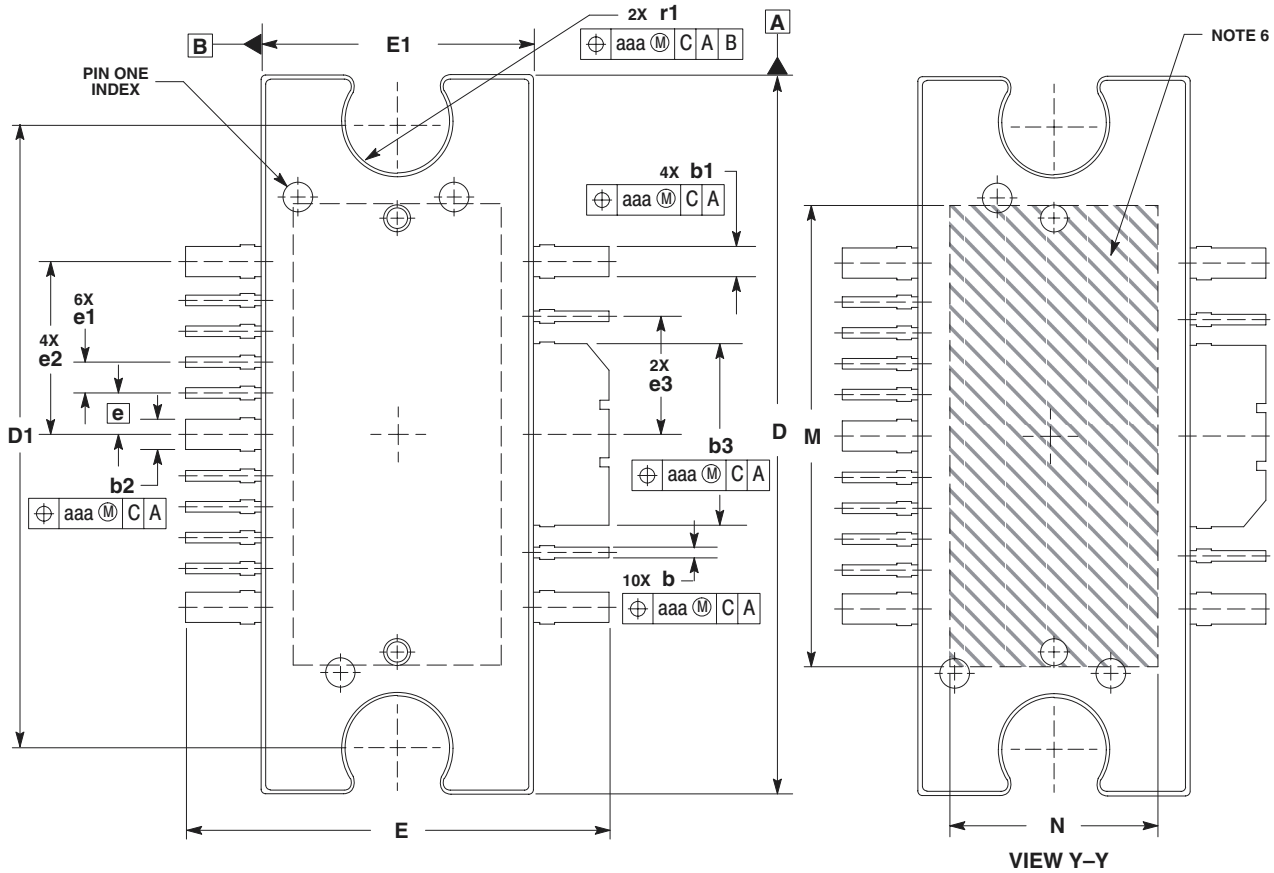


Figure 11. Series Equivalent Input and Output Impedance



# NOTES

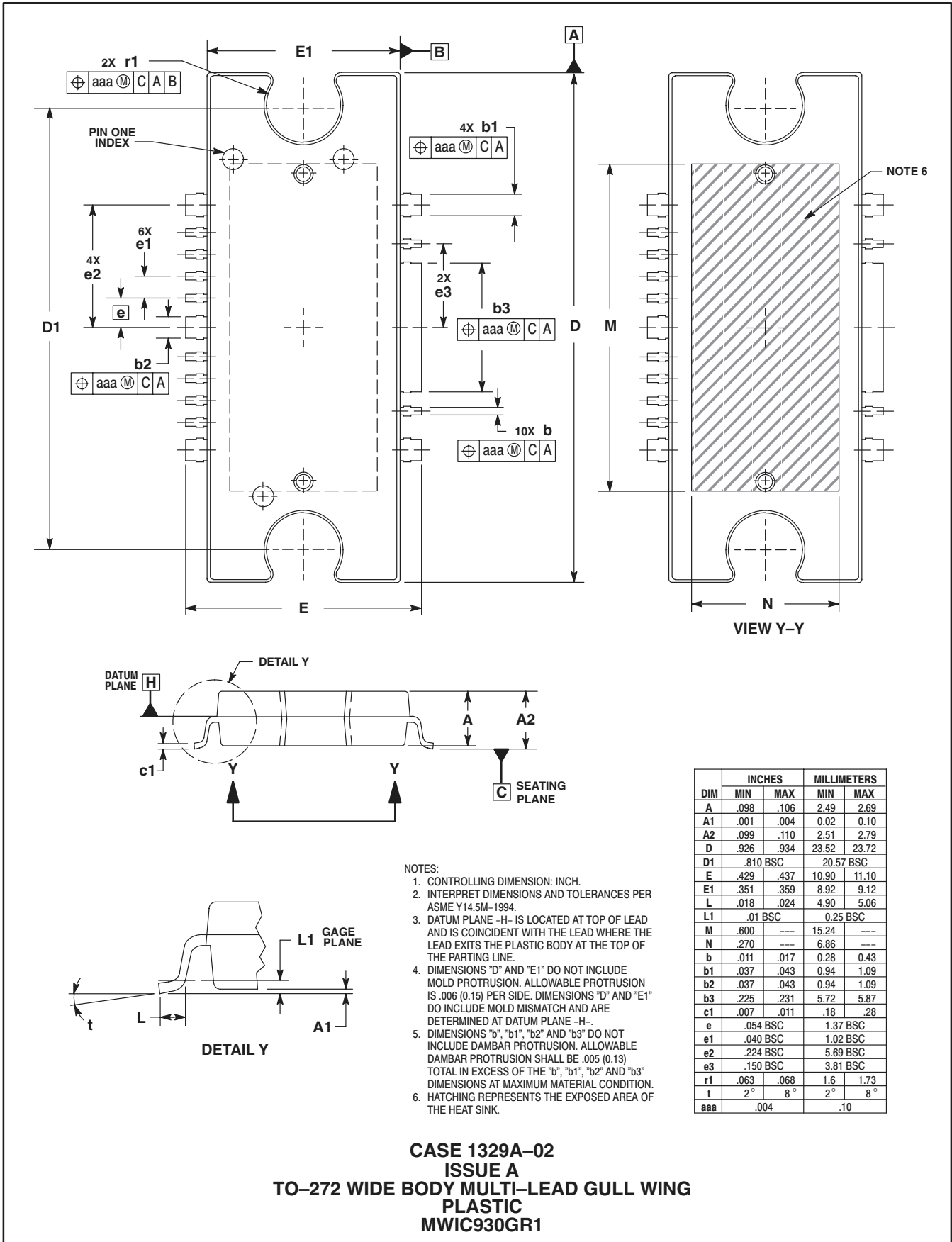
# PACKAGE DIMENSIONS



- NOTES:
1. CONTROLLING DIMENSION: INCH.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
  3. DATUM PLANE -H- IS LOCATED AT TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
  4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 (0.15) PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
  5. DIMENSIONS "b", "b1", "b2" AND "b3" DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 (0.13) TOTAL IN EXCESS OF THE "b", "b1", "b2" AND "b3" DIMENSIONS AT MAXIMUM MATERIAL CONDITION.
  6. CROSSHATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.
  7. DIM A2 APPLIES WITHIN ZONE "J" ONLY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.098	.106	2.49	2.69
A1	.038	.044	0.96	1.12
D	.926	.934	23.52	23.72
D1	.810 BSC		20.57 BSC	
E	.551	.559	14.00	14.20
E1	.351	.359	8.92	9.12
F	.025 BSC		0.64 BSC	
M	.600	---	15.24	---
N	.270	---	6.86	---
b	.011	.017	0.28	0.43
b1	.037	.043	0.94	1.09
b2	.037	.043	0.94	1.09
b3	.225	.231	5.72	5.87
c1	.007	.011	.18	.28
e	.054 BSC		1.37 BSC	
e1	.040 BSC		1.02 BSC	
e2	.224 BSC		5.69 BSC	
e3	.150 BSC		3.81 BSC	
r1	.063	.068	1.6	1.73
aaa	.004		.10	

**CASE 1329-08**  
**ISSUE H**  
**TO-272 WIDE BODY MULTI-LEAD**  
**PLASTIC**  
**MWIC930R1**



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.098	.106	2.49	2.69
A1	.001	.004	0.02	0.10
A2	.099	.110	2.51	2.79
D	.926	.934	23.52	23.72
D1	.810	BSC	20.57	BSC
E	.429	.437	10.90	11.10
E1	.351	.359	8.92	9.12
L	.018	.024	4.90	5.06
L1	.01	BSC	0.25	BSC
M	.600	---	15.24	---
N	.270	---	6.86	---
b	.011	.017	0.28	0.43
b1	.037	.043	0.94	1.09
b2	.037	.043	0.94	1.09
b3	.225	.231	5.72	5.87
c1	.007	.011	.18	.28
e	.054	BSC	1.37	BSC
e1	.040	BSC	1.02	BSC
e2	.224	BSC	5.69	BSC
e3	.150	BSC	3.81	BSC
r1	.063	.068	1.6	1.73
t	2°	8°	2°	8°
aaa	.004	---	.10	---

NOTES:

1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 (0.15) PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS "b", "b1", "b2" AND "b3" DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 (0.13) TOTAL IN EXCESS OF THE "b", "b1", "b2" AND "b3" DIMENSIONS AT MAXIMUM MATERIAL CONDITION.
6. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SINK.

**CASE 1329A-02  
ISSUE A  
TO-272 WIDE BODY MULTI-LEAD GULL WING  
PLASTIC  
MWIC930GR1**

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and the Stylized M Logo are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

Motorola and the Stylized M Logo are registered in the US Patent & Trademark Office. All other product or service names are the property of their respective owners.

© Motorola, Inc. 2003.

**How to reach us:**

**USA/EUROPE/Locations Not Listed:** Motorola Literature Distribution; P.O. Box 5405, Denver, Colorado 80217. 1-303-675-2140 or 1-800-441-2447

**JAPAN:** Motorola Japan Ltd.; SPS, Technical Information Center, 3-20-1, Minami-Azabu. Minato-ku, Tokyo 106-8573 Japan. 81-3-3440-3569

**ASIA/PACIFIC:** Motorola Semiconductors H.K. Ltd.; Silicon Harbour Centre, 2 Dai King Street, Tai Po Industrial Estate, Tai Po, N.T. Hong Kong. 852-26668334

**Technical Information Center:** 1-800-521-6274

**HOME PAGE:** <http://www.motorola.com/semiconductors>



**MOTOROLA**



**MWIC930/D**